

LESD7D5.0T5G ESD PROTECTION DIODE

Discription

The LESD7D5.0T5G is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

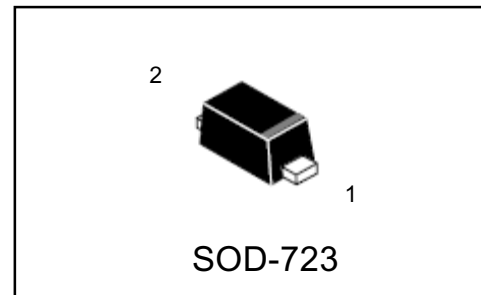
Applications

- | Cellular phones audio
- | MP3 players
- | Digital cameras
- | Portable applications
- | mobile telephone

Features

- | Small Body Outline Dimensions:
0.039" x 0.024" (1.0 mm x 0.60 mm)
- | Low Body Height: 0.017" (0.43 mm) Max
- | Stand-off Voltage: 3.3 V - 12 V
- | Low Leakage
- | Response Time is Typically < 1 ns
- | ESD Rating of Class 3 (> 16 kV) per Human Body Model
- | IEC61000-4-2 Level 4 ESD Protection
- | We declare that the material of product compliance with RoHS requirements.

LESD7D5.0T5G



Ordering information

| Device | Package | Shipping |
|--------------|---------|----------------|
| LESD7D5.0T5G | SOD-723 | 8000/Tape&Reel |

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|------------------------------------|---------------------|------------------|
| IEC61000-4-2 (ESD) | air discharge contact discharge | ± 15 ± 8 | kV |
| ESD Voltage | Per Human Body Model | 16 | kV |
| Total Power Dissipation on FR-5 Board (Note 1) @ $T_A=25^\circ\text{C}$ | PD | 150 | Mw |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | $^\circ\text{C}$ |
| Lead Solder Temperature – Maximum (10 Second Duration) | TL | 260 | $^\circ\text{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

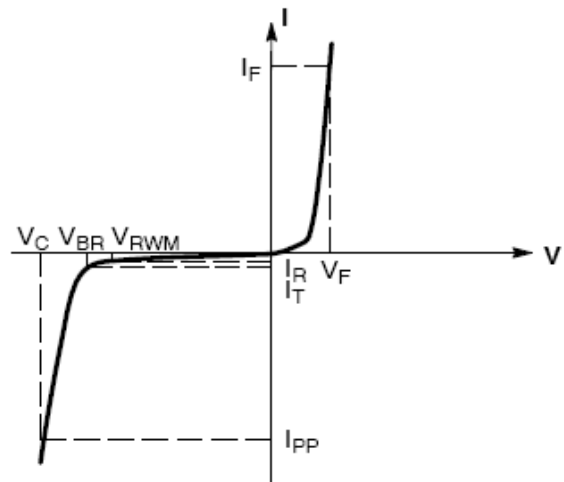
1. FR-5 = 1.0*0.75*0.62 in.

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ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

| Symbol | Parameter |
|------------------|--|
| I _{PP} | Maximum Reverse Peak Pulse Current |
| V _C | Clamping Voltage @ I _{PP} |
| V _{RWM} | Working Peak Reverse Voltage |
| I _R | Maximum Reverse Leakage Current @ V _{RWM} |
| V _{BR} | Breakdown Voltage @ I _T |
| I _T | Test Current |
| I _F | Forward Current |
| V _F | Forward Voltage @ I _F |
| P _{pk} | Peak Power Dissipation |
| C | Max. Capacitance @V _R = 0 and f = 1 MHz |



Uni-Directional TVS

ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted, V_F=0.9V Max. @ I_F=10Ma for all types)

| Device | V _{RWM} (V) | I _R (μA) @ V _{RWM} | V _{BR} (V) @ I _T (Note 2) | I _T (mA) | I _{PP} (A) (Note 3) | V _C (V) @ Max I _{PP} (Note 3) | P _{PK} (W) (8*20 μs) | C (pF) |
|--------------|-------------------------|---|--|------------------------|------------------------------------|--|-------------------------------------|-----------|
| | Max | Max | Min | | Max | Max | Typ | Typ |
| LESD7D3.3T5G | 3.3 | 2.5 | 5.0 | 1.0 | 9.8 | 10.4 | 102 | 80 |
| LESD7D5.0T5G | 5.0 | 1.0 | 6.2 | 1.0 | 8.7 | 12.3 | 107 | 65 |

Other voltage available upon request.

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C
- Surge current waveform per Figure 3.

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TYPICAL CHARACTERISTICS

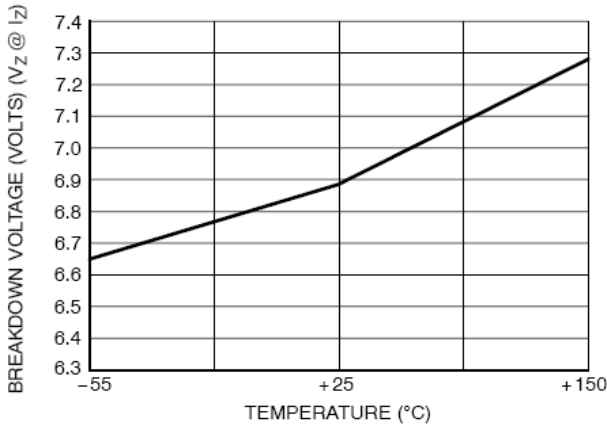


Figure 1. Typical Breakdown Voltage versus Temperature

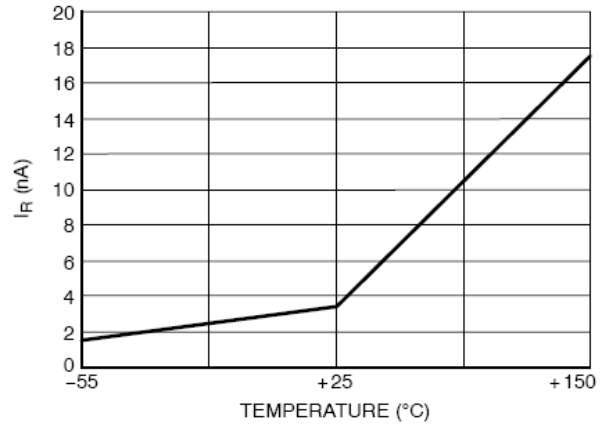


Figure 2. Typical Leakage Current versus Temperature

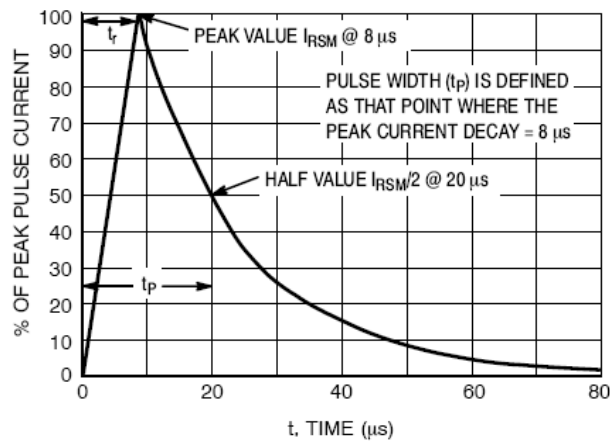


Figure 3. 8*20 μs Pulse Waveform

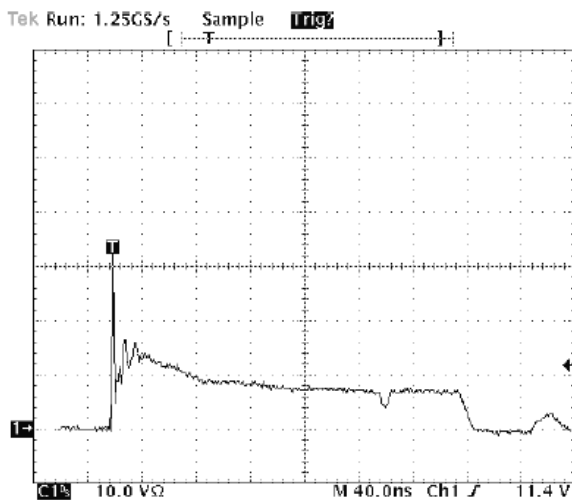


Figure 4. Positive 8kV contact per IEC 61000-4-2-LESD7D5.0T5G

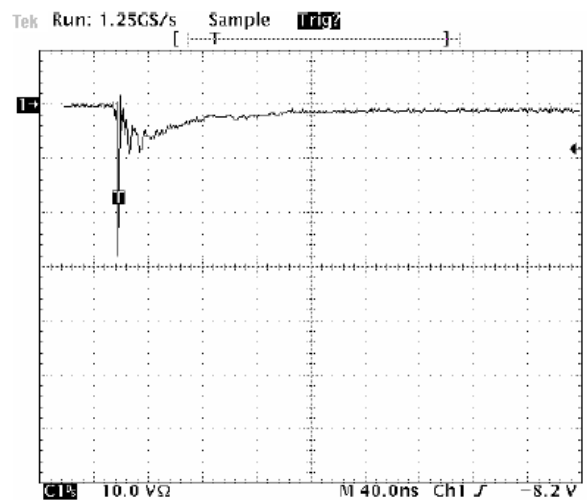
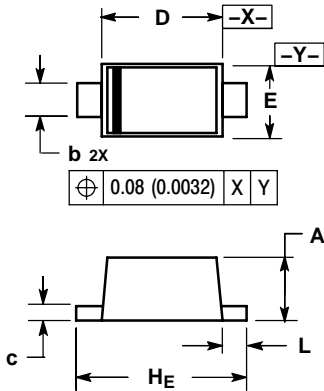


Figure 5. Negative 8kV contact per IEC 61000-4-2-LESD7D5.0T5G

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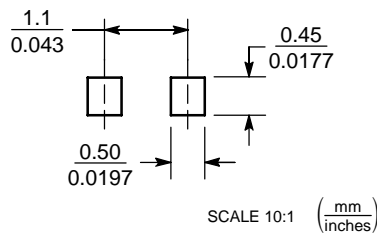
SOD-723



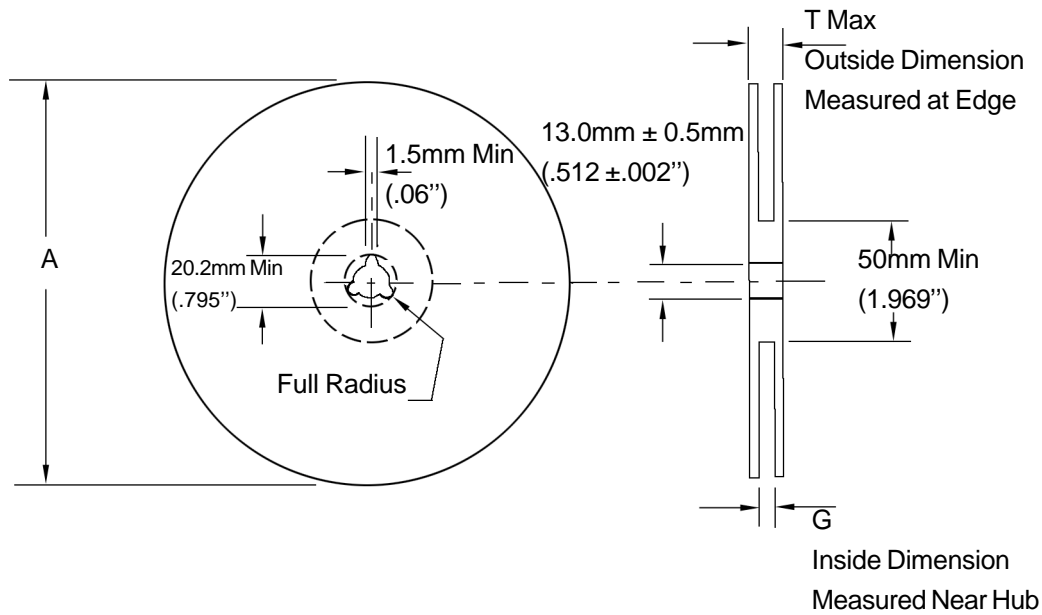
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|--------|--------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.49 | 0.52 | 0.55 | 0.019 | 0.020 | 0.022 |
| b | 0.25 | 0.28 | 0.32 | 0.0098 | 0.011 | 0.013 |
| c | 0.08 | 0.12 | 0.15 | 0.0032 | 0.0047 | 0.0059 |
| D | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| E | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 |
| HE | 1.35 | 1.40 | 1.45 | 0.053 | 0.055 | 0.057 |
| L | 0.15 | 0.20 | 0.25 | 0.006 | 0.0079 | 0.010 |

SOLDERING FOOTPRINT*



EMBOSSED TAPE AND REEL DATA FOR DISCRETES



| Size | A Max | G | T Max |
|------|--------------------|--|------------------|
| 8 mm | 330mm (12.992") | 8.4mm+1.5mm, -0.0 (.33"+.059", -0.00) | 14.4mm (.56") |

Reel Dimensions

Metric Dimensions Govern — English are in parentheses for reference only

Storage Conditions

Temperature: 5 to 40 Deg.C (20 to 30 Deg. C is preferred)
 Humidity: 30 to 80 RH (40 to 60 is preferred)
 Recommended Period: One year after manufacturing
 (This recommended period is for the soldering condition only. The characteristics and reliabilities of the products are not restricted to this limitation)

Shipment Specification

